Silicon Epitaxial Planar Switching Diode

Features

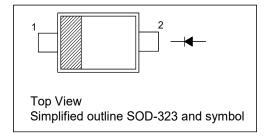
- Low Forward Voltage
- Fast Reverse Recovery Time
- Small Total Capacitance

Application

• Ultra high speed switching

PINNING

PIN	DESCRIPTION			
1	Cathode			
2	Anode			



Absolute Maximum Ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit
Maximum (Peak) Reverse Voltage	V _{RM}	85	V
Reverse Voltage	V _R	80	V
Average Rectified Forward Current	I _{F(AV)}	100	mA
Maximum (Peak) Forward Current	I _{FM}	200	mA
Surge Forward Current (10 ms)	I _{FSM}	1	А
Power Dissipation	P _{tot}	200	mW
Junction Temperature	Tj	150	°C
Storage Temperature Range	T _{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient 1)	Reja	625	°C/W

¹⁾Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



1SS352

Characteristics at $T_a = 25$ °C

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I _R = 10 μA	V _{(BR)R}	80	-	V
Forward Voltage at I _F = 100 mA	V _F	-	1.2	V
Reverse Current at $V_R = 30 \text{ V}$ at $V_R = 80 \text{ V}$	I _R	-	0.1 0.5	μΑ
Total Capacitance at $V_R = 0 V$, $f = 1 MHz$	Ст	-	3	pF
Reverse Recovery Time at I_F = 10 mA, I_{RR} = 0.1 * I_R , V_R = 6 V, R_L = 100 Ω	t _{rr}	-	4	ns



Electrical Characteristics Curves

Fig 1. Power Derating Curve

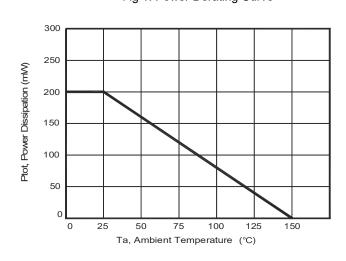


Fig 2. Total Capacitance vs. Reverse Voltage

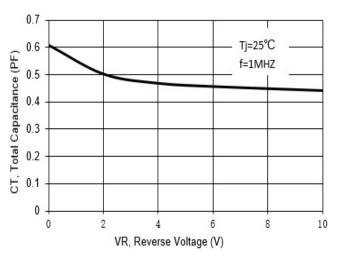


Fig 3. Reverse Current vs. Reverse Voltage

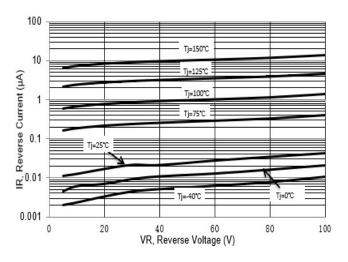
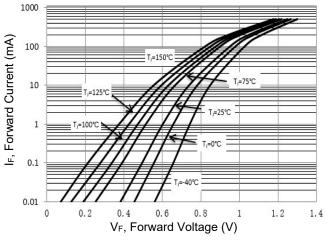


Fig 4. Forward Characteristics

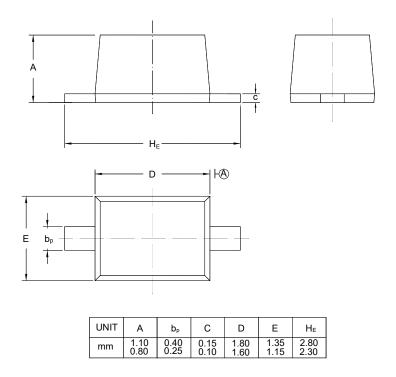




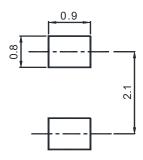
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



Recommended Soldering Footprint



Packing information

Tape Width		Pit	Pitch		Size	Day Book Booking Overtity
Раскаде	Package (mm)	mm	(inch)	mm	(inch)	Per Reel Packing Quantity
SOD-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" W2 " = Part No.

" III " = Cathode line

Font type: Arial



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